

DLAP-411-Orin

Edge AI Platform Powered by NVIDIA® Jetson AGX Orin™

Preliminary



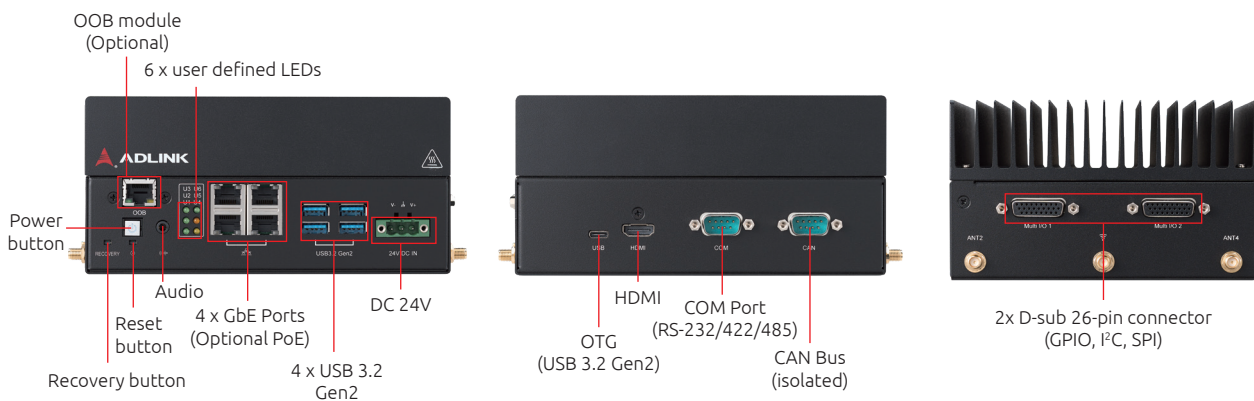
AIIXON Scalable. EdgeGO

Features

- NVIDIA® Jetson AGX Orin processing/inference engine 8/12-core Carmel Arm 64-bit CPU, 1792/2048-Core Ampere GPU, 32/64GB LPDDR5, 64 GB eMMC with 56/64 Tensor Cores
- Fanless compact inference platform
- 4 GbE POE Port (Optional), 4 USB 3.2 Gen2, 1 OTG/Type C USB 3.2 Gen2, 1 CAN bus (isolated) 1 COM (RS-232/422/485), IO connector (GPIO, I²C, SPI)
- 6 user defined LEDs, 1 Audio, 1 HDMI.
- Edge AI model management and OTA (over the air) provisioning powered by Scalable
- Monitoring, alerts and updates are empowered by Allxon Device Management Solutions (Allxon DMS)
- Remote control by Allxon Out-Of-Band (OOB) (optional)
- An Edge-Native and Web-Based Platform that Simplifies Configuration, Monitoring, and Consolidation of Applications Running on Connected Devices by EdgeGO
- 24 V DC input, OCP
- Operating Temp: -20 to +55°C
- Compact Size: 175(W) x 145(D) x 85(H) (mm)

Software Support

- Linux Ubuntu 20.04/22.04



Ordering Information

DLAP-411-Orin w/ PSE	Powered by NVIDIA® Jetson AGX Orin™ 32GB, support 4 GbE Ports (PoE)
DLAP-411-Orin	Powered by NVIDIA® Jetson AGX Orin™ 32GB
DLAP-411-Orin 64GB	Powered by NVIDIA® Jetson AGX Orin™ 64GB
DLAP-411-Orin w/ PSE 64GB	Powered by NVIDIA® Jetson AGX Orin™ 64GB
DLAP-411-Orin w/ PSE w/ OOB	Powered by NVIDIA® Jetson AGX Orin™ 32GB, support 4 GbE Ports (PoE) , OOB module
DLAP-411-Orin w/ OOB	Powered by NVIDIA® Jetson AGX Orin™ 32GB,OOB module

Optional Accessories

GST160A24-AD	Power adapter, for DLAP-411-Orin w/o PSE OP Temp Max: 55°C For DLAP-411-Orin w/ PSE OP Temp Max: 40°C
GST220A24-AD	Power adapter, for DLAP-411-Orin w/ PSE OP Temp Max: 55°C
THALES MV31-W	5G module, M.2 B-key 3042 5G-FR1/4G/3G module
Quectel RM520N-GL	5G module, M.2 B-key 5G/4G/3G/GNSS module QUECTEL_RM520N-GL
Sierra EM7565	4G/LTE module, M.2 B-key LTE/HSPA+ module Sierra Wireless, EM7565
ENL-R8852BE	Wi-Fi 6 module, Wi-Fi 6 (11a/b/g/n/ac/ax 2Tx2R) + BT (V5.2) M.2 Type 2230 Combo Module LITEON_ENL-R8852BE(RTL8852BE)
ASDEM8EDE-128GP0	Temp.-25°C to +85°C M.2 2280 PCIe Gen3x4
ASDEM8EDE-256GP0	Temp.-25°C to +85°C M.2 2280 PCIe Gen3x4
ASDEM8EDE-512GP0	Temp.-25°C to +85°C M.2 2280 PCIe Gen3x4
ASDEM8EDE-1TBT0	Temp.-25°C to +85°C M.2 2280 PCIe Gen3x4
ASDEM8EDE-2TBT0	Temp.-25°C to +85°C M.2 2280 PCIe Gen3x4

Specifications

Model	Jetson AGX Orin 32GB	Jetson AGX Orin 64GB
System Core		
GPU	NVIDIA Ampere architecture with 1792 NVIDIA® CUDA® cores and 56 Tensor Cores	NVIDIA Ampere architecture with 2048 NVIDIA® CUDA® cores and 64 Tensor Cores
CPU	8-core Arm® Cortex®-A78AE v8.2 64-bit CPU 2MB L2 + 4MB L3	12-core Arm® Cortex®-A78AE v8.2 64-bit CPU 3MB L2 + 6MB L3
RAM	32GB 256-bit LPDDR5	64GB 256-bit LPDDR5
Storage	64GB eMMC 5.1	
OS	Linux® Ubuntu	
Front Panel I/O Ports		
Button	1x power, 1x reset, 1x recovery	
HDMI	1x HDMI (Max. resolution 3840x2160 @ 60Hz)	
USB	4x USB 3.2 Gen2 Type-A	
Ethernet	4x 10/100/1000Mbps Ethernets (Optional PoE support, IEEE 802.3af/at)	
Audio	Mic-in, line-out	
Side Panel I/O Ports		
I/O Connector	2x D-sub 26-pin connector (GPIO, I ² C, SPI)	
Back Panel I/O Ports		
USB	1x USB 3.2 Gen2 Type-C (OTG)	
Serial Port	1x COM RS-232/RS-422/RS-485 (DB9)	
CAN Bus	1x 2.0b, isolated (DB9)	
Extension		
M.2	1x M.2 M key 2242 and 2280 PCIe Gen4 1x M.2 B key 3042 and 3052 for 5G/LTE M.2 E key 2230 for Wifi 5/6	
SD Card Slot	1x Micro SIM Slot (support)	
Out-Of-Band (OOB)	Support Ethernet and Wifi, monitoring and managing at remote locations (thermal sensor, remote power on/off, restart, monitor debug port detection device status.)	
LED indicator		
LED	6x user defined LEDs	
Power Requirements		
DC Input	24V (OVP,OCP)	
AC Input	160 up to 220W power adapter	
Power switch	1x Power ON/OFF Button (AT/ATX , Default : AT)	
Mechanical		
Dimensions (W x D x H)	175x 145x 85mm	
Weight	2.2kg	
Mounting	Wall mount, VESA DIN rail (optional)	
SMA Antenna Connector	6	
Environmental		
Operating Temperature	Standard -20°C to 55°C with Air Flow 0.6 m/s (system level), -25°C to 85°C (board level)	
Operating Humidity	~95% @40°C (non-condensing, optional with fanless solution)	
Storage Temperature	-40°C to +85°C	
Vibration	Operating 5Grms, 5-500Hz, 3 axes w/M.2 SSD	
Shock	Operating 100G, half sine 11ms duration w/ SD, M.2 SSD	
ESD	Contact ± 4kV, Air ± 8kV	
Regularity	CE & FCC class B, (EN61000-6-4/-6-2), CE-LVD & UL by CB, FCCID	
Internal		
Thermal sensor	1x Thermal sensor	
F/W Support		
WDT	WDT supported	